



Holography and 3D Imaging: Tomorrows Ultimate Experience

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Message from the Guest Editor

Dear Colleagues,

Today, holograms are standard security issue on bankcards and bank notes, event tickets, postage stamps and passports; aimed specifically to halt counterfeiting. They are a typical component in the validation of safety critical items, such as medicines and machine parts, and therefore save lives. The list of applications of holography will increase in length as a growing number of five-star research labs in Universities and Technical companies, including Microsoft, find new applications for these amazing devices. Researchers are developing new types of holograms with the long-term aim of progressing the medium beyond its ability to simply capture and replay three-dimensional images, pursuing their general ability to diffract and manipulate light. In this Special Issue we explore some new major developments that point the way for unique collaboration between creative computing and synthetic holograms within numerous applications including the arts, entertainment, games, mobile applications, multimedia, web design and other pervasive interactive systems.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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